## System Configuration/Role of Each Line and Component

In semiconductor manufacturing processes, etching equipment, sputtering equipment, ion implantation equipment, and CVD equipment generally process wafers and LCD's in a vacuum chamber.

The peripheral equipment used to exhaust (vacuum) air from and supply atmospheric pressure to the vacuum chamber, such as valves, regulators, pressure switches, cylinders and gate valves should meet conditions such as non-leakage, clean specifications, and corrosion resistance.

#### System Configuration (Typical Application) Vacuum gauge High vacuum Transfer chamb manual angle Vacuum rodless cylinder CYV\* valve XLH XL High vacuum double acting valve XLC Process chamber it valve (insert type Smooth vent XGT Digital Clean valve Dry pump (cassette type) XGT regulator Clean XVD flow gas filter SR□ switch PF2A SF Diffusion element Exhaust line ① (stainless steel)\* Load-lock chambe Digital pressure switch N<sub>2</sub> gas/air supply line 3 ZSE80 Direct operated 2/3 Digital Clean port solenoid valve regulator flow switch . VDW/VX2 High vacuum angle valve PF3W SB Filter for water XLA High vacuum smooth exhaust Turbo-molecular pump valve XLD Cooling water line 4 High vacuum rubber seal angle valve Thermo chiller/Thermo controller Dry pump HBZ/HEC Temperature adjustment line 5 Exhaust line (2) \* Available upon request. \*\* The installation example for CYV given above, is an image only, and does not satisfy all Vacuum chamber the conditions for usage. The system consists of a load lock chamber C which introduces a wafer from the

The system consists of a load lock chamber C which introduces a wafer from the clean room into the chamber, a transfer chamber B which receives a wafer and moves it in and out, and a process chamber A in which the wafer is processed. Each chamber is exhausted with a vacuum pump in order to maintain a vacuum pressure.

## **Role of Each Line and Component**

#### **Exhaust lines**

The exhaust line can be divided into the process chamber **exhaust line** ① and the transfer chamber and load-lock chamber **exhaust line** ②.

**Exhaust line** ① has a high vacuum manual angle valve (XLH) between a dry vacuum pump and a turbo-molecular pump and a high vacuum angle valve (XLC) between a turbo-molecular pump and the process chamber.

When these valves are closed, vacuum is maintained in the process chamber and maintenance can be performed on the pumps.

Also, the process gas (reaction gas) can be introduced to the process chamber by closing the high pressure angular valve.

**Exhaust line** ② is used to evacuate the transfer chamber and the load-lock chamber. The load-lock chamber is restored to atmospheric pressure temporarily while a wafer is introduced. After introduction of the wafer, air is exhausted with a dry vacuum pump. When the pressure is reduced to a certain point, the turbo-molecular pump is used for exhaust. A by-pass circuit is provided with a high-vacuum smooth exhaust valve (XLD) and a high-vacuum angle valve (XLA/XLF).

The smooth vent valve XVD is used to supply air slowly at the initial stage after opening and, on achieving a certain pressure, to switch to the main valve for a full supply to prevent particle turbulence.

### N<sub>2</sub> gas/air supply line 3

When a wafer is introduced to the load-lock chamber C, the chamber has to temporarily restore atmospheric pressure. N<sub>2</sub> or clean air is supplied for this purpose. The gas introduced to the chamber must have a high degree of cleanliness.

For fluid contact parts, stainless steel fittings are generally used. Non-leakage specification VCR® or Swagelok fittings® are adopted wherever possible. The smooth vent valve XVD is used to change the flow rate of N₂ or clean air, which is supplied slowly at the initial stage after opening and, on achieving a certain pressure, is switched to the main valve for a full supply to prevent particle turbulence.

At the entrance of the chamber, the flow is rectified with a clean gas filter (with 100% filtration efficiency of 0.01  $\mu$ m particles) and a stainless steel diffusion element inside the chamber.

### Cooling water/Temperature control line (4)(5)

In order to optimize wafer processing and deposit removal, the temperature in each chamber (especially the process chamber) is precisely controlled.

The cooling water line can be used with devices such as the 2 port solenoid valves for water (VDW/VX2), flow switch (PF3W), clean regulator (SRH), and pressure switch (ISE80).

Thermo-chillers and thermo-controllers are used to cool and maintain the chamber temperatures.

#### Slit valve/Transfer

In each chamber, vacuum and atmosphere are divided by a slit valve (XGT). Wafer transfer inside a chamber is enabled by the use of a vacuum cylinder (CYV).

XL□

XL□Q

XM□ XY□

D-U

XGT

CYV

# **Series Variations**

### **Exhaust Line**

Description	Model	Shaft seal system Valve type	Flange size	Material	
Aluminum High Vacuum Angle Valve	XLA XLAV (With solenoid valves)	Bellows seal Single acting (N.C.)	16, 25, 40, 50, 63, 80	Body: Aluminum alloy Bellows: Stainless steel 316L	
High fluorine resistance Minimal outgassing Minimal contamination from heavy metals  High fluorine resistance  Minimal contamination from heavy metals	XLC XLCV (With solenoid valves)	Bellows seal Double acting	(KF [NW]/K [DN] Note 1)		
	XLF XLFV (With solenoid valves)	O-ring seal Single acting (N.C.)	16, 25, 40, 50, 63 80, 100, 160 (KF [NW]/K [DN] Note 1)	Body: Aluminum alloy Main part: Stainless steel, FKM Note 3)	
	XLG XLGV (With solenoid valves)	O-ring seal Double acting	16, 25, 40, 50, 63 80, 100 Note 2), 160 Note 2) (KF [NW]/K [DN] Note 1))	Body: Aluminum alloy Main part: Stainless steel, FKM Note 3)	
	XLD XLDV (With solenoid valves)	Bellows/ O-ring seal 2-Step Control	25, 40, 50, 63, 80 (KF [NW]/K [DN] Note 1))	Body: Aluminum alloy Bellows: Stainless steel 316L	
O,	XLH	Manual	16, 25, 40, 50 (K [NW])		
P.1109	XLS	Single acting (N.C.)	16, 25 (KF [NW])	Body: Aluminum alloy Main part: Stainless steel, PFA, FKM Note 3)	
Aluminum One-touch Connection and Release High Vacuum Angle Valve  One-touch connection and release (No tools are required.)  P.1163	XLAQ	Bellows seal Single acting (N.C.)	16, 25, 40, 50 (KF [NW])	Body: Aluminum alloy Bellows: Stainless steel 316L	
	XLDQ	Bellows/ O-ring seal 2-Step Control	40, 50 (KF [NW])		
Stainless Steel High Vacuum Angle Valve	ХМА	Bellows seal Single acting (N.C.)	10, 20, 10, 00, 00, 00		
<ul> <li>A precision casting, unified com- position prevents accumulation of gas.</li> </ul>	хмс	Bellows seal Double acting	(KF [NW]/K [DN] Note 1)/CFNote 4)		
Series XM is interchangeable with the series XL, aluminum high vacuum angle valve.	XMD	Bellows/ O-ring seal 2-Step Control	25, 40, 50, 63, 80 (KF [NW]/K [DN] Note 1)/CFNote 4))		
P.1175	хмн	Manual	16, 25, 40, 50 (KF [NW]/CF Note 4))	Body: SCS13 (equivalent to stainless steel 304)	
Stainless Steel High Vacuum In-line Valve	XYA	Bellows seal Single acting (N.C.)	25, 40, 50, 63, 80	Bellows: Stainless steel 316L	
Combination with the angle valve allows space saving.	хүс	Bellows seal Double acting	(KF [NW]/K [DN] Note 1))		
	XYD	Bellows/ O-ring seal 2-Step Control	25, 40, 50, 63, 80 (KF [NW]/K [DN] Note 1)		
P.1175	хүн	Manual	25, 40, 50 (KF [NW])		

Note 1) Applicable to flange sizes over 63. Note 2) Made to order. Solenoid valves are not available. Note 3) Standard seal

Note 4) Only applicable to flange sizes 16, 40, and 63.

## N<sub>2</sub> Gas/Air Supply Line

Description	Model	Fitting size	Material
Smooth Vent Valve  Valve / needle valve integrated construction – requires only 1/4 the piping space of previous models.  Particulates significantly reduced through the use of a metal diaphragm in the sheet portion  Flow of both initial air supply and main air supply can be adjusted.	XVD	1/4 (For VCR®/Swagelok®)	Body: Stainless steel Main part: Stainless steel, FKM (seal material)

## **Slit Valve**

Description	Model	Opening window size Height x width (mm)	Applicable wafer size	Number of axis	Material
Siit Valve  This product is suitable for the partition valve between the load lock chamber and the transfer chamber or between the transfer chamber and the process chamber in semiconductor equipment	XGT22	32 x 222	200 mm	Two axes bellows	Body: A5052 Gate: A6063 Bellows: AM350 Seal Material: FKM, Kalrez 4079
or other equipment.		46 x 236			
Cassette type		50 x 336	300 mm	One axis bellows	
Non-Cassette type P.1211					

## **Transfer Line**

Description	Model	Bore size (mm)	Port size	Material
Rodless Cylinder for Vacuum  • Air cylinder for transfer in vacuum environments (1.3 x 10 <sup>-4</sup> Pa)  CYV  P.1219	CVV	15	5/16-24UNF	Body: Aluminum allow Linear: Stainless steel
	32	7/16-20UNF	O-ring: Fluororubber	

**SMC** 

XL□

XL□Q

XM□ XY□

D-□ XVD

XGT

CYV